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Allin et al.

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(54) **HEAT SINK ASSEMBLY**

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(73) Assignee: **Oculus VR, LLC**, Menlo Park, CA (US)

(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
USPC D13/179, 122, 182
CPC .. H05K 7/20; H05K 7/20172; H05K 7/20127; H05K 7/20336; H05K 7/202; H05K 7/20272; H01L 23/34; H01L 23/3672; H01L 23/40; H01L 23/4006; H01L 23/4093; F28D 15/0208; F28D 15/04
See application file for complete search history.

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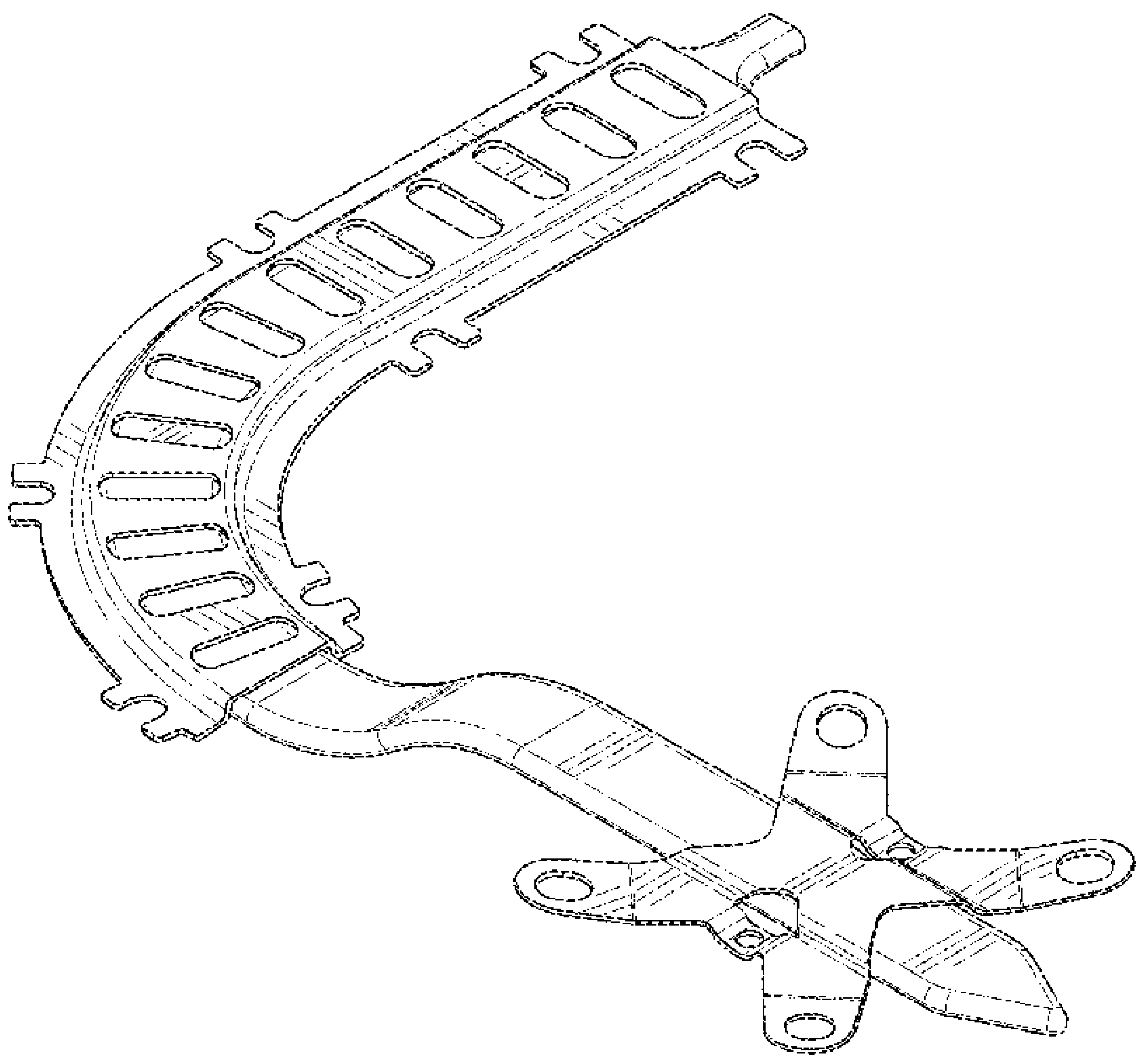
(57) **CLAIM**

The ornamental design for a heat sink assembly, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a heat sink assembly, showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a rear view thereof;
FIG. **4** is a left side view thereof;
FIG. **5** is a right side view thereof;
FIG. **6** is a top view thereof; and,
FIG. **7** is a bottom view thereof.

1 Claim, 7 Drawing Sheets



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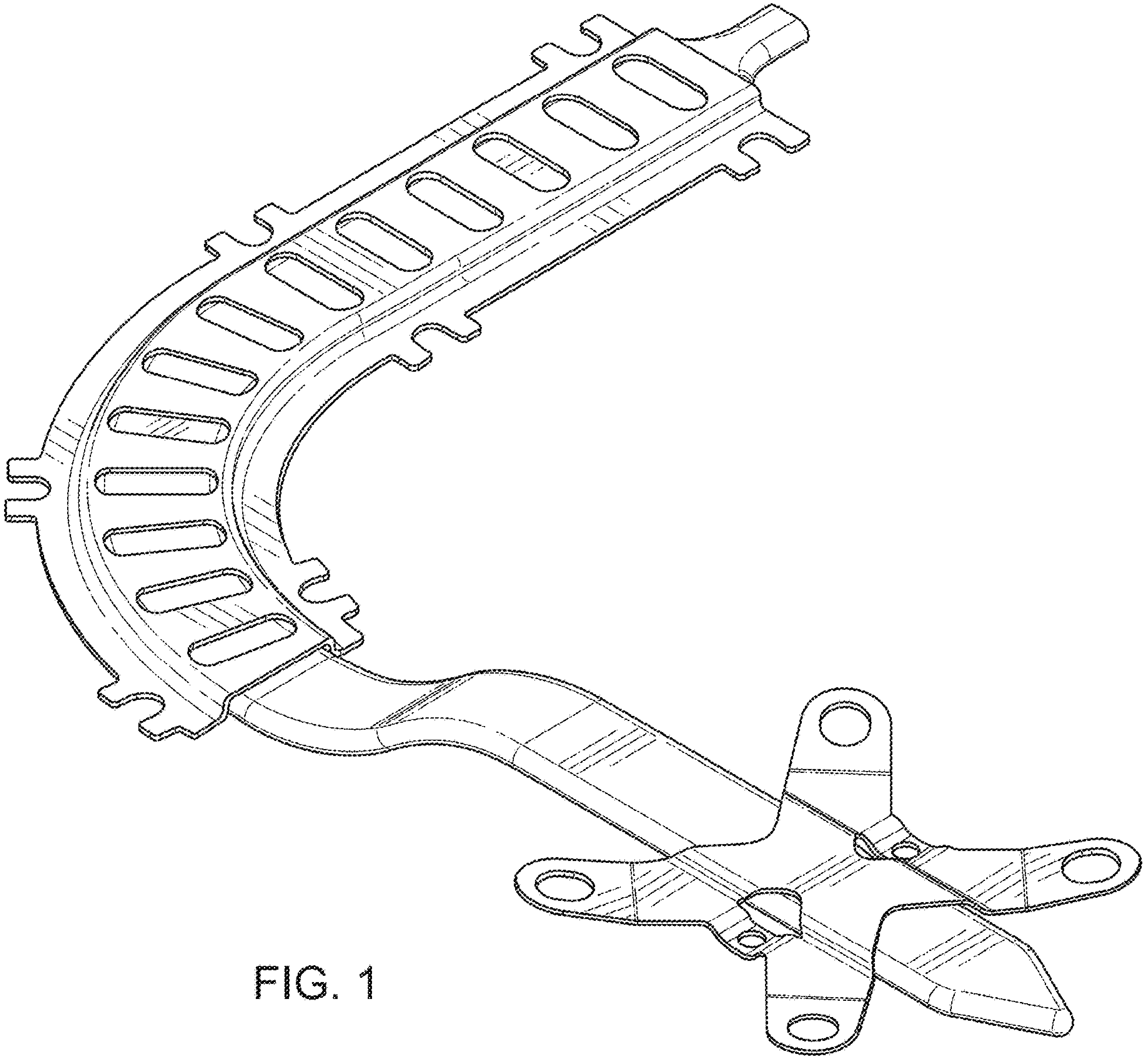

FIG. 1

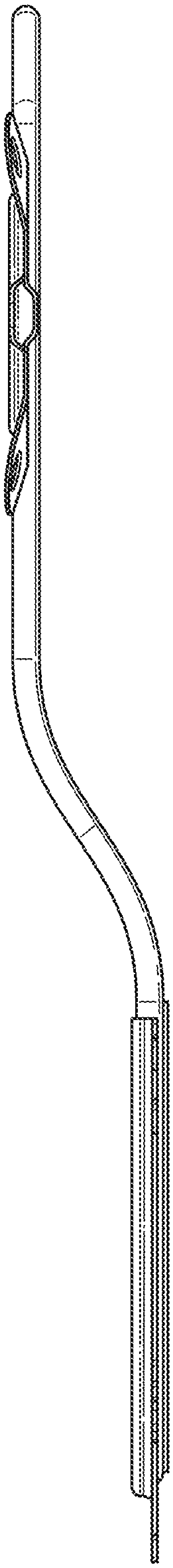

FIG. 2

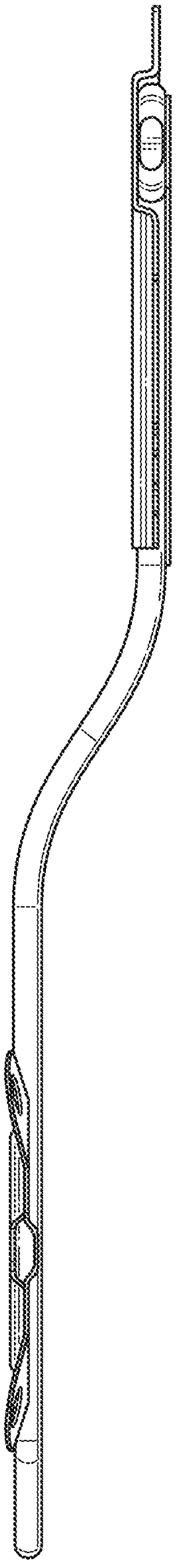

FIG. 3

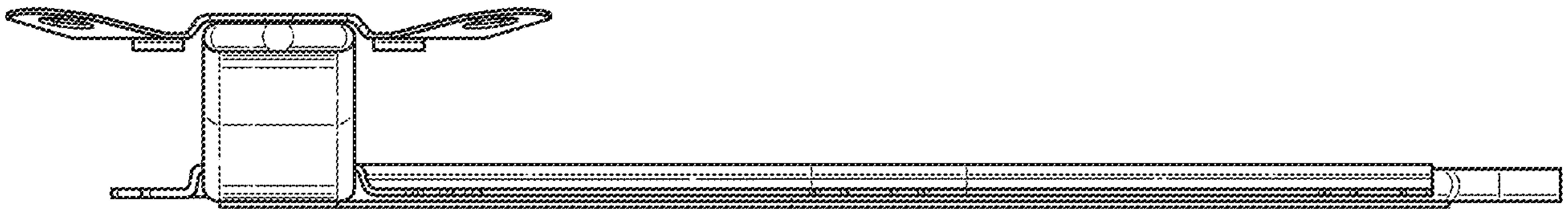

FIG. 4

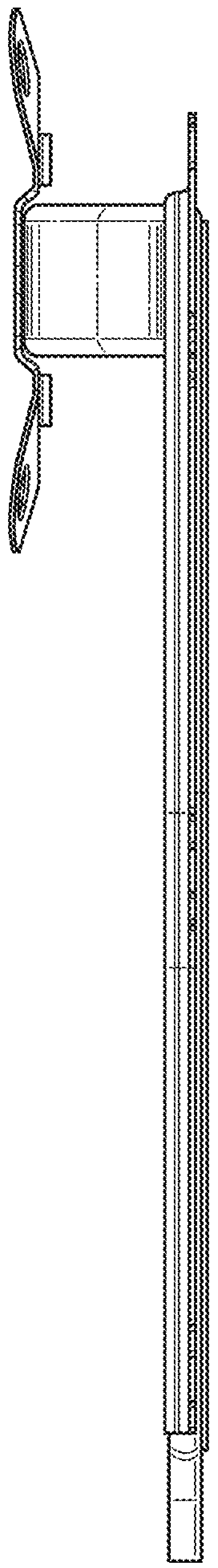

FIG. 5

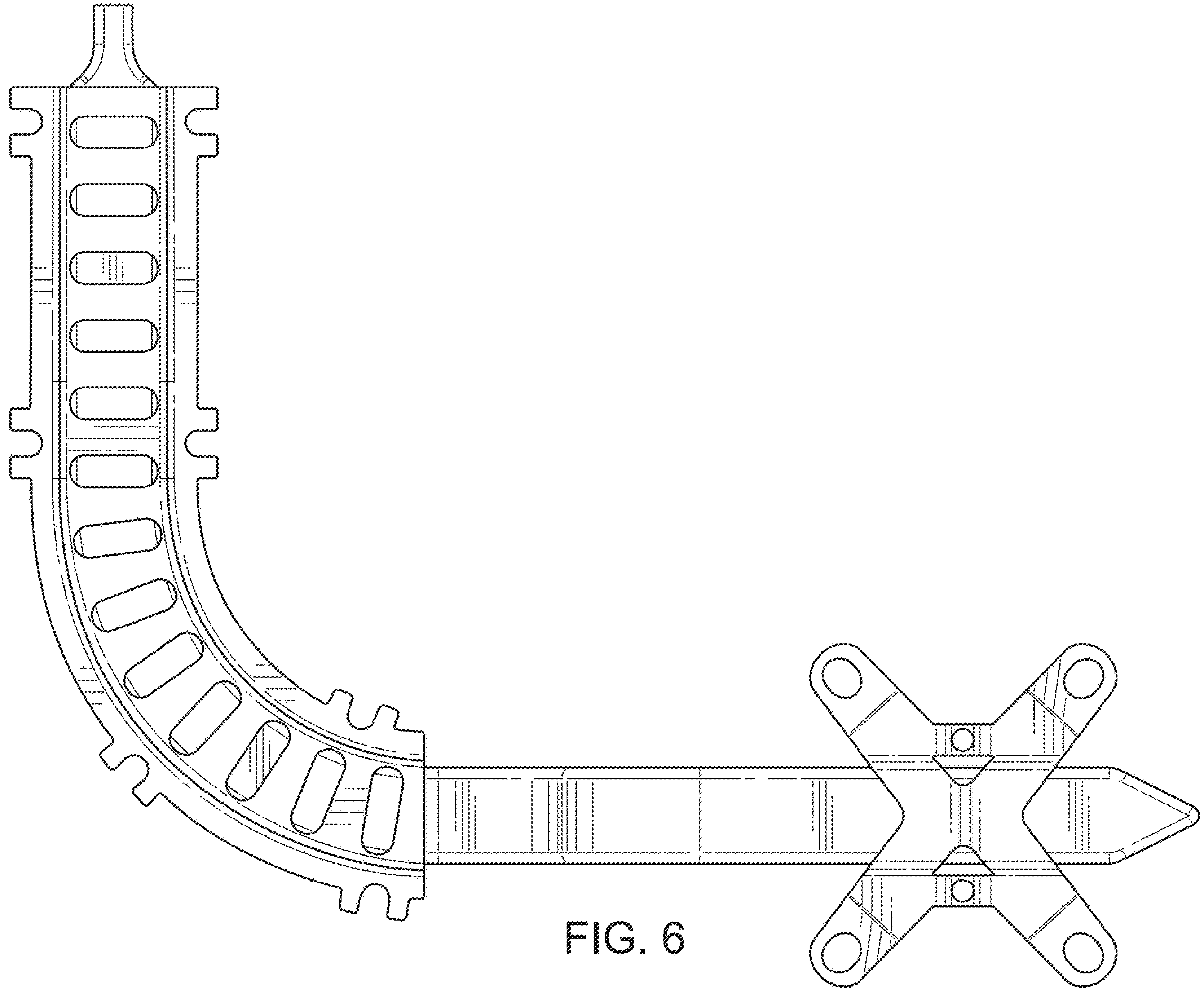

FIG. 6

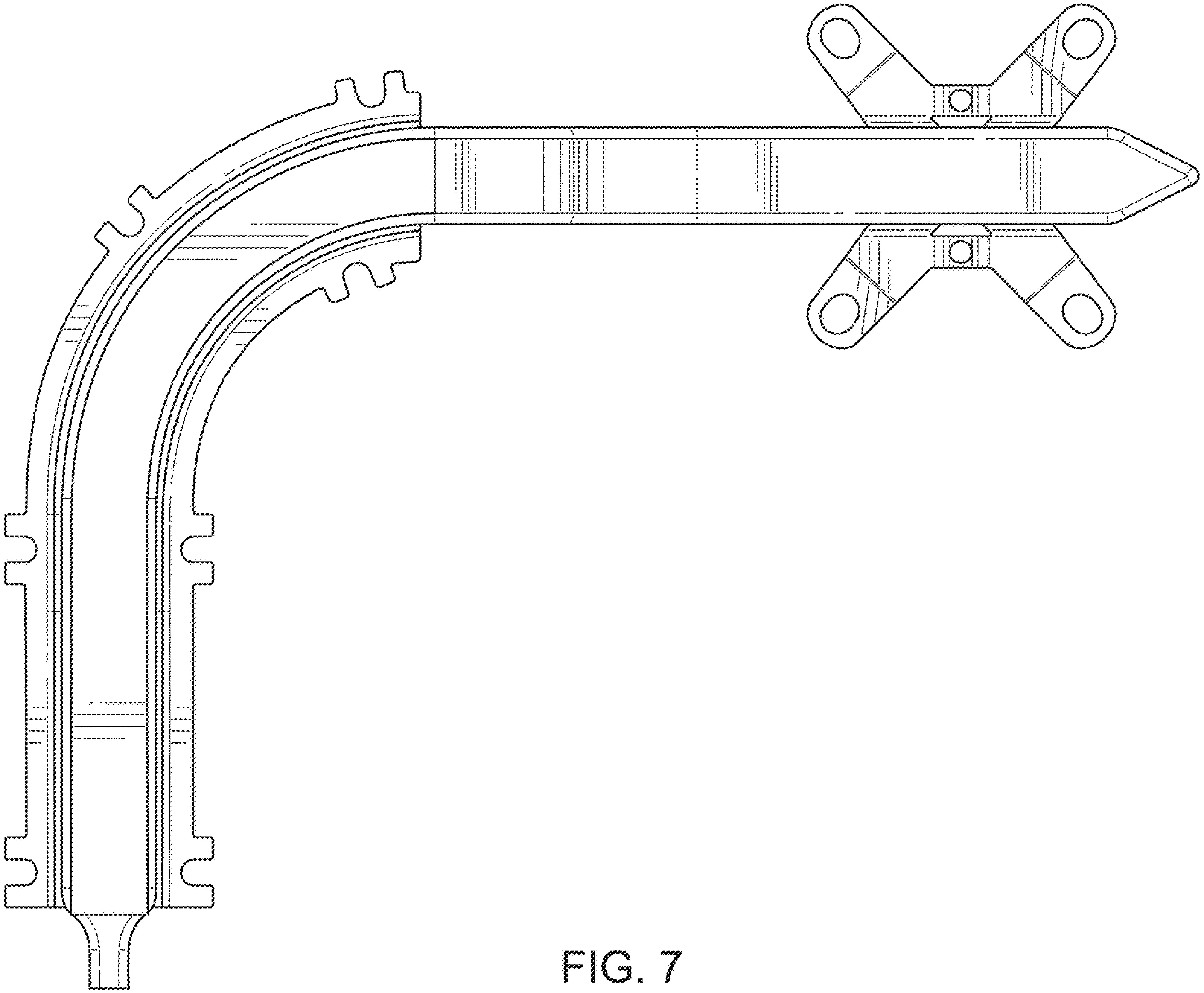

FIG. 7